

IN THE CLAIMS

Please amend the claims as follows:

Claim 1. (Currently Amended) A thermoelectric module, comprising:

a plurality of thermoelectric semiconductor chips;

first and second substrates;

a plurality of first and second electrodes formed on said first and second substrates,
respectively; and

a first solder through which said first and second electrodes are bonded to respective
end portions of said thermoelectric semiconductor chips in order to connect the plural
thermoelectric semiconductor chips in series,

said first substrate being made to include at least two protrusions that protrude toward
opposite sides which appear upon at-a-right-angle projection of the second substrate onto the
first substrate.

Claim 2. (Original) The thermoelectric module according to claim 1, wherein
concave portions, convex portions or aperture portions are formed in the protrusions of said
first substrate.

Claim 3. (Original) A method of assembling a thermoelectric module in a radiating
member, comprising the steps of:

mounting the first substrate of the thermoelectric module according to claim 1 on a
radiating member through second solder having a liquidus temperature lower than a solidus
temperature of the first solder;

holding the respective protrusions of the first substrate by leading edges of
corresponding support arms in a state where the second solder is melted, and pushing the first

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substrate toward the radiating member under pressure while rocking the first substrate in a direction orthogonal to the pushing direction.

Claim 4. (Original) The method according to claim 3, wherein the leading edges of the support arms are engaged with the concave portions, the convex portions or the aperture portions, and the first substrate is pushed under pressure and rocked by the support arms.

Claim 5. (Original) The method according to claim 3, wherein a temperature difference between a liquidus temperature of the second solder and a solidus temperature of the first solder is set to be lower than 40 °C.